

## Claims

What is claimed is:

1. A heat sink-type cooling device for an integrated circuit comprising a base and plurality of fin extended upward from the end surface of said base, characterized in that,

said plurality of fin divided into more than one heat zone, wherein there is drop height between each two zones.

2. The heat sink-type cooling device for an integrated circuit according to claim 1, wherein said plurality of fin is framed by bending a mental plate.

3. The heat sink-type cooling device for an integrated circuit according to claim 1, wherein said plurality of fin is constructed by more than one vertical plate and plurality of horizontal plate where said plurality of horizontal plate is connected to said vertical plate by turns.

4. A heat sink-type cooling device for an integrated circuit comprising a base and plurality of fin

extended upward from the end surface of said base, characterized in that,

    said plurality of fin divided into more than one heat zone with drop height between each two zones, and said plurality of fin framed by bending a mental plate into more than one vertical plate and plurality of horizontal plate, wherein said plurality of horizontal plate is connected to said vertical plate by turns, and each of those horizontal plates which is not connected to the end surface of said base is punched with a rectangular hole.

5. The heat sink-type cooling device for an integrated circuit according to claim 4, wherein said plurality of fin is firstly punched with rectangular holes on said horizontal plates and then is bended to form heat zones with drop height between each two zones.

6. The heat sink-type cooling device for an integrated circuit according to claim 4, wherein said plurality of fin is punched with rectangular holes

and simultaneously is bended to form heat zones with drop height between each two zones.

7. A heat sink-type cooling device for an integrated circuit comprising a base and plurality of fin extended upward from the end surface of said base, characterized in that,

    said plurality of fin is divided into more than one heat zone, wherein there is drop height between each two zones and each zone is separately framed by bending a mental plate.